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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

912

APPL NUM 10052989	FILING DATE 11/09/2001	CLASS 438	SUBCLASS 612	GAU 2812	EXAMINER D. Vu
<b>**APPLICANTS:</b> Hsieh Han-Kun; Wang Shing-Ru; Tung I-Chung; 2818					
<b>**CONTINUING DATA VERIFIED:</b> 10930-22477					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> TAIWAN 90118363 07/27/2001					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO YUSO-131	
<b>TITLE :</b> Formation of electroplate solder on an organic circuit board for flip chip joints and board to board solder joints					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
Assistant Examiner		<b>DRAWING</b>	
<b>ISSUE FEE</b>		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Primary Examiner Application Examiner	
<input type="checkbox"/> <b>PREPARED FOR ISSUE</b>		<b>WARNING:</b> The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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